



Collective and Extrinsic Effects on Transport in 2D Materials

Zlatan Aksamija

Department of Electrical and Computer Engineering University of Massachusetts Amherst zlatana@engin.umass.edu

http://netlab.umasscreate.net

lab



NETIab @ UMass Amherst

Hamburg 2019

1

Motivation







Poiseuille/Ziman regime: phonons act as a gas in a pipe

Cepellotti et al., Nat. Commun. 6, 6400, 2015.

Lee et al., Nat. Commun. 6, 6290, 2015.

Methodology

Phonon dispersion calculated from firstprinciples using Quantum Espresso



Goes into the phonon- Boltzmann Transport Equation (BTE)

$$\frac{\partial n_{q,b}}{\partial t} + v_{q,b}. \nabla n_{q,b} = -\left(\frac{\partial n_{q,b}}{\partial t}\right)_{\text{collision}}$$

$$\left(\frac{\mathbf{n}_{\mathbf{q},\mathbf{b}}-\boldsymbol{n}_{q0}}{\boldsymbol{\tau}_R}\right) + \left(\frac{\mathbf{n}_{\mathbf{q},\mathbf{b}}-\boldsymbol{n}_{q0}^*}{\boldsymbol{\tau}_N}\right)$$

$$n_{q0} = \left(e^{\hbar\omega_q/K_BT} - 1\right)^{-1}, \ n_{q0}^* = \left(e^{(\hbar\omega_q/K_BT) + \vec{\Lambda}.\vec{q}} - 1\right)^{-2}$$

4. E. McCann and M. Koshino, Rep. Prog. Phys. 76, 5, 2013

NETIab @ UMass Amherst



Phonon transport with edge roughness

Model using the steady-state phonon Boltzmann transport equation

$$\vec{v}_{\vec{q}} \cdot \nabla_{\vec{r}} T \frac{\partial N_{\vec{q}}^0(T)}{\partial T} + v_{\perp}(\vec{q}) \frac{\partial n_{\vec{q}}(y)}{\partial y} = \frac{n_{\vec{q}}(y)}{\tau_{int.}(\vec{q})}$$
In the absence of boundaries, RTA solution: $R_{\vec{q}} = \tau_{int.}(\vec{q})\vec{v}_{\vec{q}} \cdot \nabla_{\vec{r}} T \frac{\partial N_{\vec{q}}^0(T)}{\partial T}$
Each boundary
contributes one term:
 $p(\vec{q}) \exp\left[-W/\Lambda_{int.}^{\perp}(\vec{q})\right]$
Sum the infinite series:
 $n_{\vec{q}}^+(y) = R_{\vec{q}} \left\{ 1 - \frac{[1 - p(\vec{q})] \exp\left[-y/\Lambda_{int.}^{\perp}(\vec{q})\right]}{1 - p(\vec{q}) \exp\left[-W/\Lambda_{int.}^{\perp}(\vec{q})\right]} \right\}$

Heat flux weaker near edges due to roughness scattering

Hamburg 2019

Position Dependence of Thermal Conductivity

UMassAmherst

Heat flux (resolved by position "y")

$$\vec{Q}^+(y) = \hbar \sum_{q^\perp > 0} \omega(\vec{q}) \vec{v}_{\vec{q}} n^+_{\vec{q}}(y)$$

Thermal conductivity (from Fourier's Law)

$$\kappa^{+/-}(y) = |\vec{Q}^{+/-}(y)|/|\nabla T|$$



Wide versus narrow – in narrow ribbons (a,b) transport is dominated by edges and LER scattering, in wide ones (c,d) thermal transport dominated by internal (phonon-phonon)

Thermal transport in GNRs is size dependent

dependent UMassAmherst



Z. Aksamija and I. Knezevic, Appl. Phys. Lett. v.98, 141919 (2011)

Thermal transport in narrow GNRs is anisotropic UMassAmherst

- Angular depence of thermal conductivity reveals rich and complex behavior, especially in narrow and rough ribbons
- Zig-zag edge ribbons have up to 20% higher thermal conductivity than their armchair counterparts



NETIab @ UMass Amherst

Thermal transport in supported graphene

- Substrate scattering due to van der Waals interaction
- Results agree closely with experimental data
 (Seol et al., Science 2010)
- Drastic reduction in narrow GNR samples
- Thermal transport in narrow GNRs is highly anisotropic





UMassAmherst

NETIab @ UMass Amherst

Ballistic-to-diffusive transition in short GNRs

UMassAmherst

- Collaboration with Eric Pop's group (UIUC/Stanford)
- Transport in short GNRs is partially ballistic when length is comparable to twice the phonon meanfree-path (~100 nm)

a 'Large' L, W » λ (diffusive) **b** 'Short' $L \sim \lambda$, W » λ (quasi-ballistic) **cold cold cold**



Bae, Li, Aksamija, et al., Nature Comm. 4, 1734 (2013)

Phonon transport across a single GB

UMassAmherst

Thermal transport in graphene GBs





Yasaei et al., Nano Lett. 15, 4532, 2015

Grain boundaries deteriorate conductivity of a material, both thermal as well as electrical.

Thermal conductivity varies strongly with GB mismatch angle

Explained by phonon scattering from GB disorder



NETIab @ UMass Amherst



Thermal transport in CVD-grown graphene

NETIab @ UMass Amherst

Hamburg 2019

11

Length divergence in suspended ribbons



Xu et al., Nat. Commun. 5, 3720 (2014). Lindsay et al., Phys. Rev. B 89, 155426 (2014). Park et al, J. Appl. Phys. 114, 053506 (2013). **A.K. Majee and Z. Aksamija Phys. Rev. B 93, 235423,2016.**

Effect of width and edge roughness



Strong width dependence of thermal conductivity in graphene ribbons arising from the dependence of normal contribution and the interplay between LER and normal scattering

A.K. Majee and Z. Aksamija Phys. Rev. B 93, 235423,2016.

Methodology (contd.)

UMassAmherst



5. P.B. Allen, Phys. Rev. B 88, 144302,2013.

Methodology (contd.)

UMassAmherst

 $\kappa_{tot}(\Omega) = \kappa_{\rm C}(\Omega) + \kappa_{\rm N}(\Omega)$ Heat current in Fourier space $\vec{J}(\Omega) = \sum_{\alpha} \hbar \omega_q v_q \Phi_q(\Omega) = -\kappa(\Omega) \nabla T(\Omega)$ $= \kappa_{\rm C}(\Omega) + \sum_{i} \frac{\lambda_{1,b}(\Omega)\lambda_{2,b}(\Omega)}{\lambda_{3,b}(\Omega)}$ We get two components of thermal conductivity $\kappa_{C}(\Omega) = \frac{1}{A\delta} \sum_{a,b} \hbar \omega_{q,b} v_{\parallel}^{2}(q,b) \frac{\tau_{C}(q,b)}{1 + j\Omega\tau_{C}(q,b)} \frac{\partial n_{q,b}}{\partial T}$ Thermal conductivity due to singlemode relaxation approximation $\lambda_{1,b}(\Omega) = \frac{1}{A\delta} \sum_{q,b} q_{\parallel} v_{\parallel}(q,b) \frac{\tau_{C}(q,b)}{1+j\Omega\tau_{C}(q,b)} \frac{\partial n_{q,b}}{\partial T}$ $\lambda_{2,b}(\Omega) = \frac{1}{A\delta} \sum_{q,b} q_{\parallel} v_{\parallel}(q,b) \frac{\tau_{C}(q,b)/\tau_{N}(q,b)}{1+j\Omega\tau_{C}(q,b)} \frac{\partial n_{q,b}}{\partial T}$ Correction to thermal conductivity due to collective excitation of phonons due to anharmonic phonon-phonon processes $\lambda_{3,b}(\Omega) = \frac{1}{A\delta} \sum_{n,b} \frac{q_{\parallel}^2}{\hbar\omega_{q,b}} \left[1 - \frac{\tau_C(q,b)/\tau_N(q,b)}{1 + j\Omega\tau_C(q,b)} \right] \frac{\partial n_{q,b}}{\partial T}$

NETIab @ UMass Amherst

Frequency-dependent thermal conductivity



A. K. Majee and Z. Aksamija, Phys. Rev. B 98, 024303 (2018)

Analogous to frequency-dependence of electrical conductivity

$$\kappa(\Omega) = \frac{\kappa_0}{1 + j\Omega\tau_C}$$

Resembles low pass thermal filter with cut-off frequency defined as the frequency where $\kappa(\Omega_C) = 0.707\kappa_0$

Curves	Length (µm)	Width (μm)
	100	100
	10	10
	10	1.5

(b) (a) k^{-1} 1500 1400 4000 3900 1200 ${\sf Re}[\kappa_{\sf eff}(\Omega,{\sf Q})]~({\sf W}~{\sf m}^{-1})$ $m[\kappa_{eff}(\Omega, Q)]$ 3000 3000 1000 1000 800 2000 2000 600 500 1000 1000 400 200 20 0 10⁶ 10¹² 10¹⁰ 10⁷ 10⁴ 10⁵ 10⁶ Q (m⁻¹) 10⁸ 10⁶ Ω (s⁻¹) Q⁻¹ (m) Length (µm) Width (µm) Curves $\frac{\sum_{q,b} \hbar \omega_{q,b} v_{\parallel}^2(q,b) \frac{\tau_C(q,b)}{1+j\Omega\tau_C(q,b)} \frac{\partial n_{q,b}}{\partial T}}{\partial T}$ 100 100 *mean free path =* 10 10 $\sum_{q,b} \hbar \omega_{q,b} \, v_{\parallel}(q,b) \, \frac{\partial n_{q,b}}{\partial T}$ 10 1.5

Low-pass filter like response

NETlab @ UMass Amherst

Hamburg 2019

17

Resistive and normal contribution



Conclusion (pt. 1)



- UMassAmherst
- Dynamical response of thermal conductivity resembles like a low-pass thermal filter characteristics.
- The equivalent circuit has both resistance and capacitance---the latter arising from energy stored by phonons between their scattering events
- The cut-off frequency is found to be proportional to the scattering rates
- Can be tuned over a wide range—100 MHz to 10 GHz —by varying ribbon size and temperature.
- This technique could be used to probe phonon mean-free-path spectrum



Growing interest in lateral 2D heterostructures



UMassAmherst

(2016)

а

NETIab @ UMass Amherst

Graphene-MoS₂ heterojunction FET

UMassAmherst







SEM (left) and Raman map (right) of individual MoS₂ flake grown between graphene electrodes

е



Behranginia et al. Small 1604301 (2017)

NETIab @ UMass Amherst

Band structure calculation and alignment at the interface



NETIab @ UMass Amherst

Hamburg 2019



Calculation of grain boundary resistance



Using Landauer formalism, we compute interface conductance



- Transport occurs inside the Fermi window
- Transmission depends on gate voltage due to band alignment



NETIab @ UMass Amherst

Nomenclature of the type of interfaces

UMassAmherst

interface

<u>In homojunctions (same material on either side of the interface):</u>



Graphene-Graphene GB resistance

UMassAmherst

Twin GBs ($\theta_L = \theta_R$)

No transmission gap.

Even large mismatch angles don't lead to very high GB resistance.





NETIab @ UMass Amherst

MoS₂-MoS₂ GB resistance

UMassAmherst



NETIab @ UMass Amherst

Graphene-MoS₂ interface resistance

UMassAmherst

Class I interface

 $(\boldsymbol{\theta}_L = \boldsymbol{\theta}_R)$

No transmission gap.

Shows negligible angle dependence.

Exhibits strong dependence on carrier density.

Class II interface $(\theta_L = 0^\circ, \theta_R = \theta_M)$

Transmission gap opens up with increasing mismatch angles.

Exhibit a very strong dependence on both mismatch angle and carrier density.



Comparison of interface/GB resistance

UMassAmherst



NETIab @ UMass Amherst

UMassAmherst



Majee, Foss, and Aksamija, Sci. Rep. 7, 16597, 2017

Majee, Kommini, and Aksamija, Ann. Phys.(Berlin), 531, 1800510 (2019)

NETIab @ UMass Amherst



- Most heat generated in a 2D material based device dissipates into the supporting substrate.
- Hence, the thermal (2D/3D) interface formed strongly dictates the capabilities of thermal management in 2D devices.

Nature Nano., vol. 6, p. 147–150, (2011). 2D Mater. **4** (2017) 035027

What is the best substrate for 2D/3D TBC?

Can we map constituent material properties to the TBC and identify materials for improved TBC?

Methodology

• The substrate scattering rate based on Fermi's Golden Rule

$$\Gamma_{sub}(\omega) = \frac{\pi}{2} \frac{D_{sub}(\omega)}{m_{sub}m_{2D}} \frac{K_a^2}{\omega^2}$$

Then use a Landauer formalism to calculate the TBC G(T):

$$G(T) = \int C_{2D}(\omega, T) D_{2D}(\omega) \Gamma_{sub}(\omega) d\omega$$

- G(T) (TBC) roughly follows K_a^2
- However, we want to decouple the influence of K_a and material properties on the TBC.
- At a constant K_a , $\Gamma_{sub} \propto \frac{1}{\omega^2} \rightarrow$ low-energy, long-waveleng phonons contribute most to TBC.
- 42 interfaces studied (6 2D layers and 7 substrates).



2D-layer phonon dispersion on substrate



Temperature dependent TBC



Assuming the same coupling (K_a) throughout:

2D materials on amorphous substrates consistently show higher TBC than crystalline substrates.

Foss and Aksamija, 2D Mater. 6 (2019) 025019

Phonon Density of States (DOS)



DOS of crystalline materials follows the **Debye model** at low energies

$$D_{sub}(\omega) = 3 \frac{\omega^2}{2\pi^2 v_{sub}^3}$$

Amorphous materials deviate from the Debye model due to the randomization of atomic positions.

Leading to a large peak in the DOS of amorphous materials, often termed the **Boson Peak**.

Recall, $\Gamma_{sub}(\omega) \propto \frac{1}{\omega^2}$

Foss and Aksamija, 2D Mater. 6 (2019) 025019

Correlation between TBC and material properties \triangleleft - WSe₂ 🕁 -h-BN O - Graphene - MoS₂ - MoSe₂ \triangleright - WS₂ \sim $TBC = G(T) = \int C_{2D}(\omega, T) D_{2D}(\omega) \Gamma_{sub}(\omega) d\omega$ ALO diamond $\Gamma_{sub}(\omega) = \frac{\pi}{2} \frac{D_{sub}(\omega)}{m_{sub}m_{2D}} \frac{K_a^2}{\omega^2}$ 10 10 TBC (MWm⁻²K⁻¹) 00 TBC (MWm⁻²K⁻¹) 00 TBC (MWm⁻²K⁻¹ Debye model for substrate DOS: $D_{sub}(\omega) = 3 \frac{\omega^2}{2\pi^2 v_{sub}^3}$ 10⁻¹³ 10⁻¹⁵ 10⁻¹⁴ 10⁻¹² 10⁰ 10⁻¹ 1/(m_{2D}m_{sub}v³_{sub} $\Theta_{2D}^{}/\Theta_{sub}$ $1/(m_{2D}m_{sub}\Theta_{sub}^3)$ $\Gamma_{sub}(\omega) = \frac{3}{4\pi} \frac{K_a^2}{m_{2D}m_{sub}v_{sub}^3}$ TBC (MWm⁻²K⁻¹) TBC (MWm⁻²K⁻¹) 00 FBC (MWm⁻²K⁻¹ Analytical approximations: $\tilde{G}_1(T) \approx \frac{3}{4\pi} \frac{K_a^2}{m_{2D} m_{sub} v_{sub}^3} C_{2D}^{\nu}(T)$ 10⁰ 10⁻¹⁴ 10⁻¹⁰ 10⁻¹³ 10-12 10-11 10-11 $\tilde{G}_2(T) \approx \frac{1}{4\pi} \frac{K_a^2}{m_{2D} v_{sub}^3 \rho_{sub}} C_{2D}^v(T)$ $1/(m_{2D}^{V}v_{sub}\Theta_{sub}^{2}\rho_{sub}^{P}BW_{ZA})$ $1/(m_{2D}v_{sub}^{3}\rho_{sub}$ $1/(m_{2D}^{}v_{sub}^{3}\rho_{sub}^{}BW_{ZA}^{})$

Foss and Aksamija, 2D Mater. 6 (2019) 025019

@ 200V

TBC as a function of Boson Peak location



Foss and Aksamija, 2D Mater. 6 (2019) 025019

Conclusion (pt. 2)

- Amorphous substrates enable better heat transfer across a 2D-3D interface due to their large DOS near low energies (Boson Peak) which maximizes $\Gamma_{sub} \propto \frac{1}{\omega^2}$.
- There is a tradeoff between improved 2D/3D TBC and thermal conductivity of the substrate
 - Amorphous: good TBC, poor κ Crystalline: poor TBC, (typically) good κ
- hBN demonstrates superior TBC than our other tested 2D-layers due to its light atomic mass and flatter ZA branch dispersion.
- The TBC between 2D-materials and crystalline substrates strongly follows the inverse of the product of:
 - Atomic mass of the 2D-layer
 - Sound velocity of the substrate
 - Mass density of the substrate

- Debye temperature of the substrate squared
- Phonon bandwidth of the ZA branch of the 2D material

i.e., for 2D materials on crystal substrates **TBC** $\propto \frac{1}{m_{2D}v_{sub}\Theta_{sub}^2\rho_{sub}BW_{ZA}}$.

Acknowledgement: this work was supported by the National Science Foundation Emerging Frontiers in Research and Innovation (EFRI) grant

Questions?



Electrical transport in a CVD-grown graphene

UMassAmherst



Huang et al., Nature 09718, Vol 469 (2011) 389–393



Nemes-Incze et al., Appl. Phys. Lett. 99, (2011), 023104

Resistivity across a single GB varies from 10^2 to $10^{15} \Omega \mu m$. How does a CVD-grown graphene sheet conduct electricity?

NETIab @ UMass Amherst

UMassAmherst

Literature on graphene GB resistance





Huang et al., Nature 469, 2011



Device or study	$ ho_{\mathrm{GB}} \left(\Omega \ \mu \mathrm{m} \right)$	Measurement	Fabrication/grain notes
Device 2 (Fig. S4)	8±8	This study	Electropolished Cu, APCVD, hexagonal grains
Device 1 (Fig. 3)	120 ± 60		
Device 3 (Fig. S5)	150 ± 30		
Huang ¹¹	<60	AC-EFM	LPCVD, dendritic/Flower patchwork grains
Clark ¹²	43-140	4-Probe STM	Electropolished Cu
			APCVD, hexagonal grains
Tsen ¹³	650-3200	Resistive	LPCVD (2 Torr)
			Patchwork grains
	12900-43000	Resistive	Formed Cu pocket, ³²
			LPCVD (2 Torr), dendritic / flower grains
Yu ⁹	8400	Resistive	APCVD, hexagonal grains
Jauregui ¹⁰	2000-15000	Resistive	APCVD, hexagonal grains

Grosse et al., Appl. Phys. Lett. 105, 2014

NETIab @ UMass Amherst

Hamburg 2019

Liu et al., J.

C, 2014

Phys. Chem.

Isacsson et al., 2D Mater. 4 (2016), 012002

UMassAmherst

CVD-grown graphene



Nemes-Incze et al., Appli. Phys. Lett. 99, (2011), 023104

Simulating CVD graphene



Avrami-Johnson-Mehl method

Perpendicular bisector method

Ferenc et al., Physica A 385 (2007), 518–526

NETIab @ UMass Amherst

Simulation set-up to calculate thermal conductivity

UMassAmherst



NETIab @ UMass Amherst

Adapting the model for electron transport

 V_{i5} G_{i5} V_{i1} I_{i1} G_{i4} V_{i4} I_{i4} G_{i2} I_{i2} $I_{i3}G_{i3}$ • V_{i2} I^l_{supp} V_{i3}

In steady state, the net current through the GB=0

$$\sum_{j} I_{ji} + I^{i}_{supp} = 0$$

$$\sum_{j} (V_i - V_j) G_{ij} + I^i_{supp} = 0$$

UMassAmherst

Solve for potential of each grain iteratively

$$V_i^{n+1} = \frac{G_{ij}V_i^n + I_{supp,i}}{G_{ij}}$$

Until
$$\Delta V_i = \left| \frac{V_i^{n+1} - V_i^n}{V_i^{n+1}} \right| < tolerance$$

Hamburg 2019

 $n \mid 1$

for all the grains

 G_{ij} comprises of grain resistance and GB resistance due to mismatch angle.

NETIab @ UMass Amherst

UMassAmherst



Steady-state voltage profile



Average steady-state conductance= $3.5 \times 10^{-7} \Omega^{-1}$

NETIab @ UMass Amherst

UMassAmherst

Angular conductance is



Average conductance is 0.649 µS

NETIab @ UMass Amherst

Constructing non-straight Grain boundaries

UMassAmherst



Grains boundaries are seldom straight lines



Linear colormap showing GB resistance of each segment of the GB.

Huang et al., Nature 09718, Vol 469 (2011) 389–393

NETlab @ UMass Amherst

UMassAmherst

Despite local GB resistivity being very high (Gohms), the effective resistivity of non-straight GBs is far lower (1-10 kOhm)

Variation due to randomly generated GBs

Possible impact on variability of devices or interconnect made from CVD-grown material



NETIab @ UMass Amherst